



Lasers

Applications

Our recent solutions

IR, >60 W, >200 kHz up to MHz

Cutting/scribing of semicon structures on wafers

<1 ppm absorption optics

Trends of laser-based semiconductor processing market and our solutions to it

Green, >30 W, >200 kHz up to MHz

PV processing  
PCB selective drilling

Active automation solution

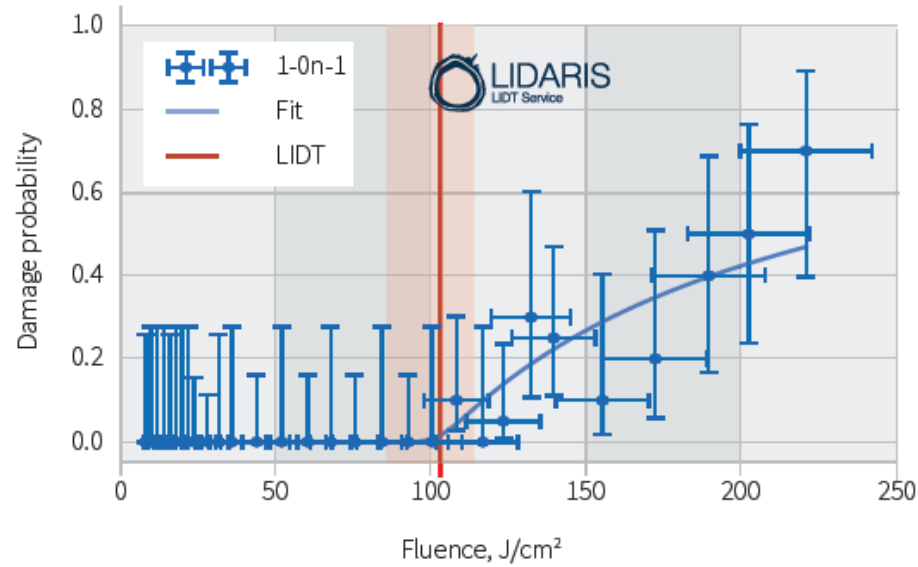
UV, >20 W, >200 kHz up to MHz

Repair of LED  
PCB/FPC drilling and cutting

Beam shaping



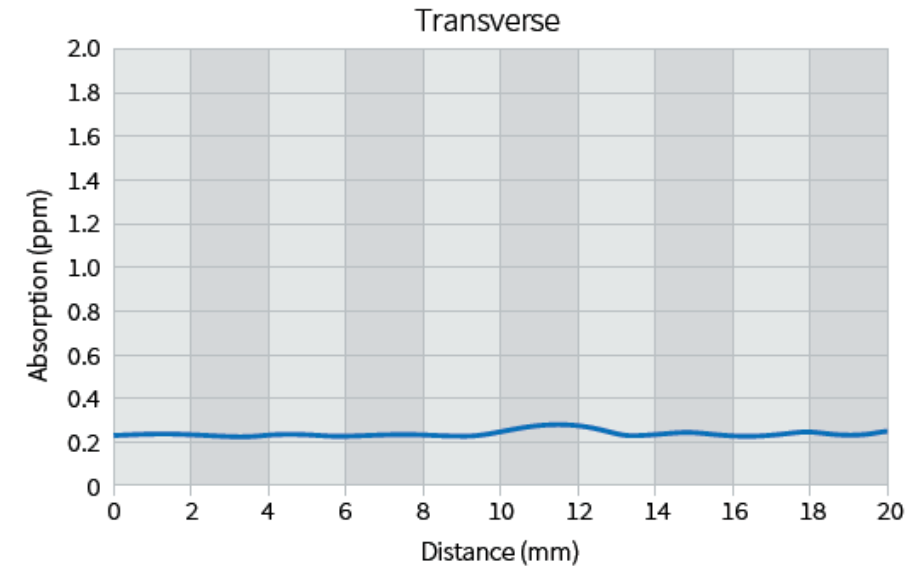
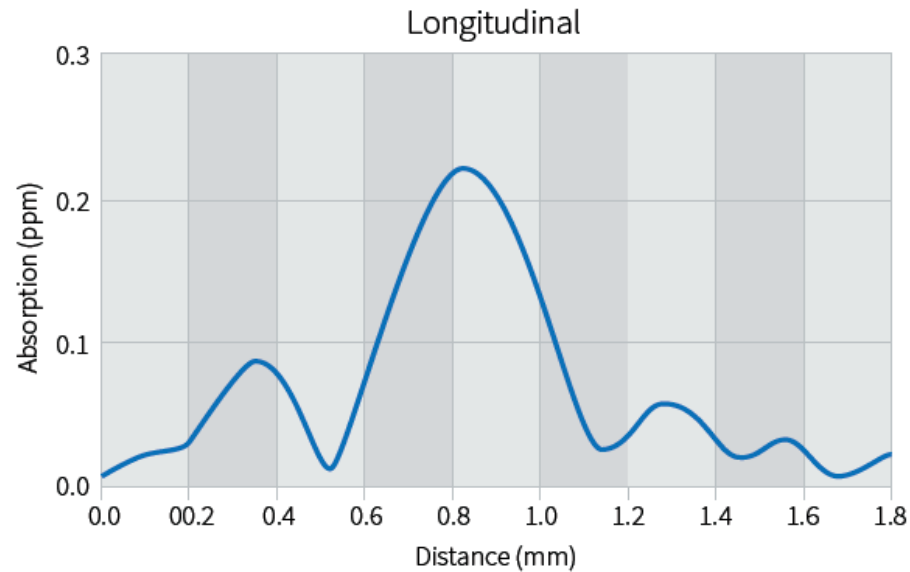
13 organizations involved developing this solution so far



IR, >60 W, >200 kHz up to MHz

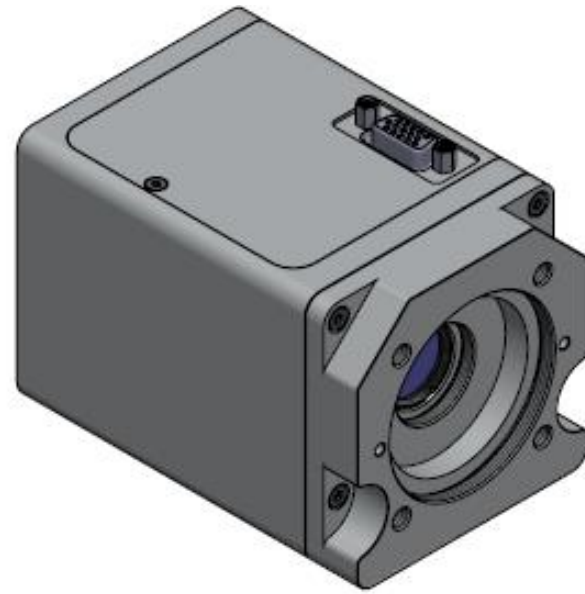
Cutting/scribing of semicon structures on wafers

<1 ppm absorption optics





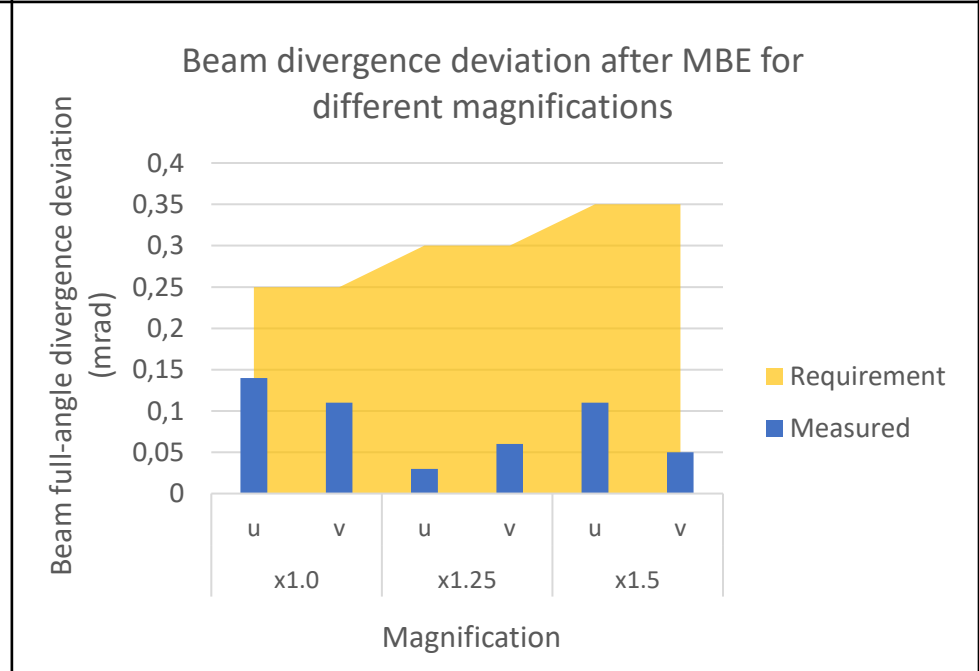
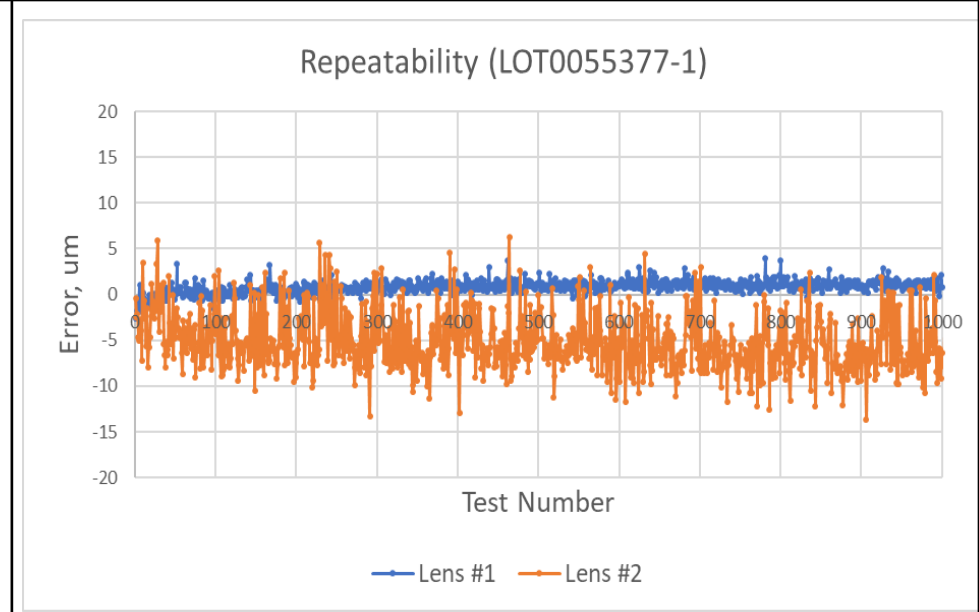
9 partners involved  
developing this solution  
so far



Green, >30 W, >200 kHz up to MHz

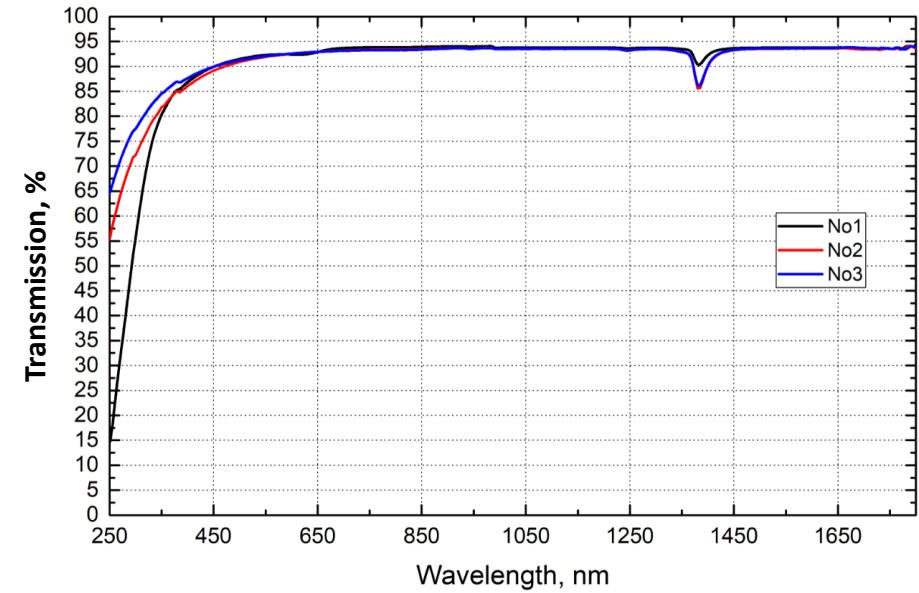
PV processing  
PCB selective drilling

Active automation solution

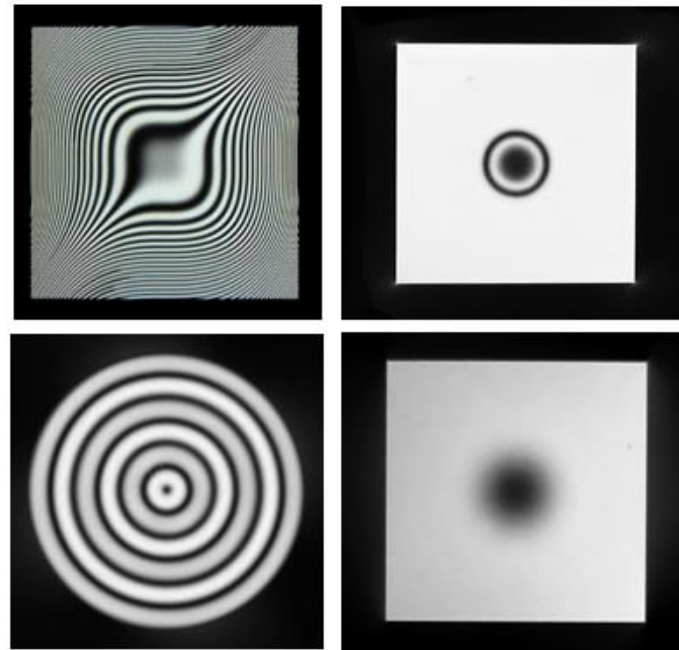




Period from 100  $\mu\text{m}$  to 10  $\mu\text{m}$ :



One of the most successful technology transfer from university to production for us



UV, >20 W, >200 kHz up to MHz

Repair of LED  
PCB/FPC drilling and cutting

Beam shaping



Collaboration is the key to success